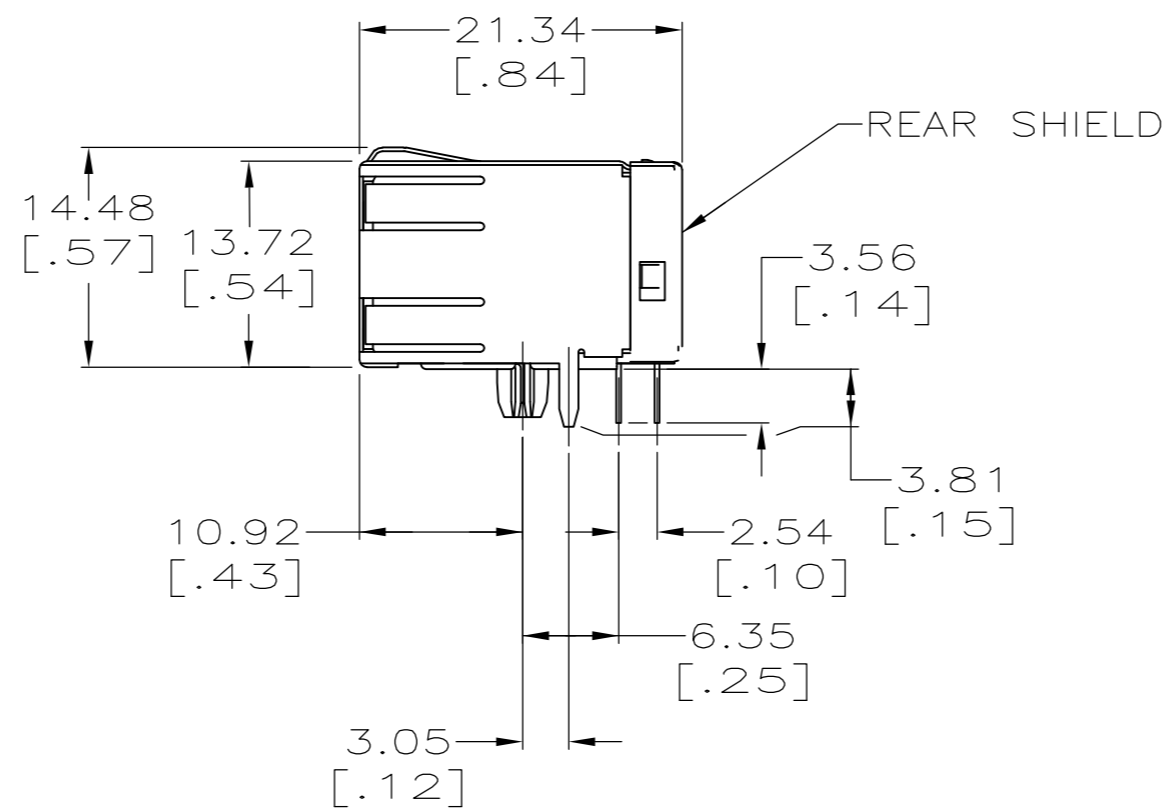
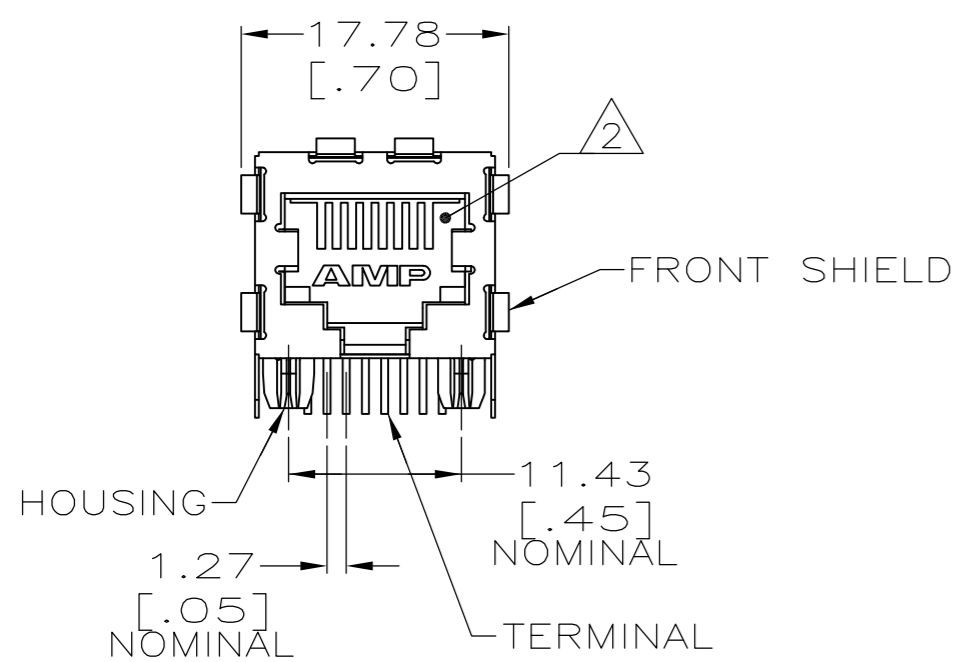


LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
AA	22	D	ECR-11-024835	20FEB2012	JJ	AC	

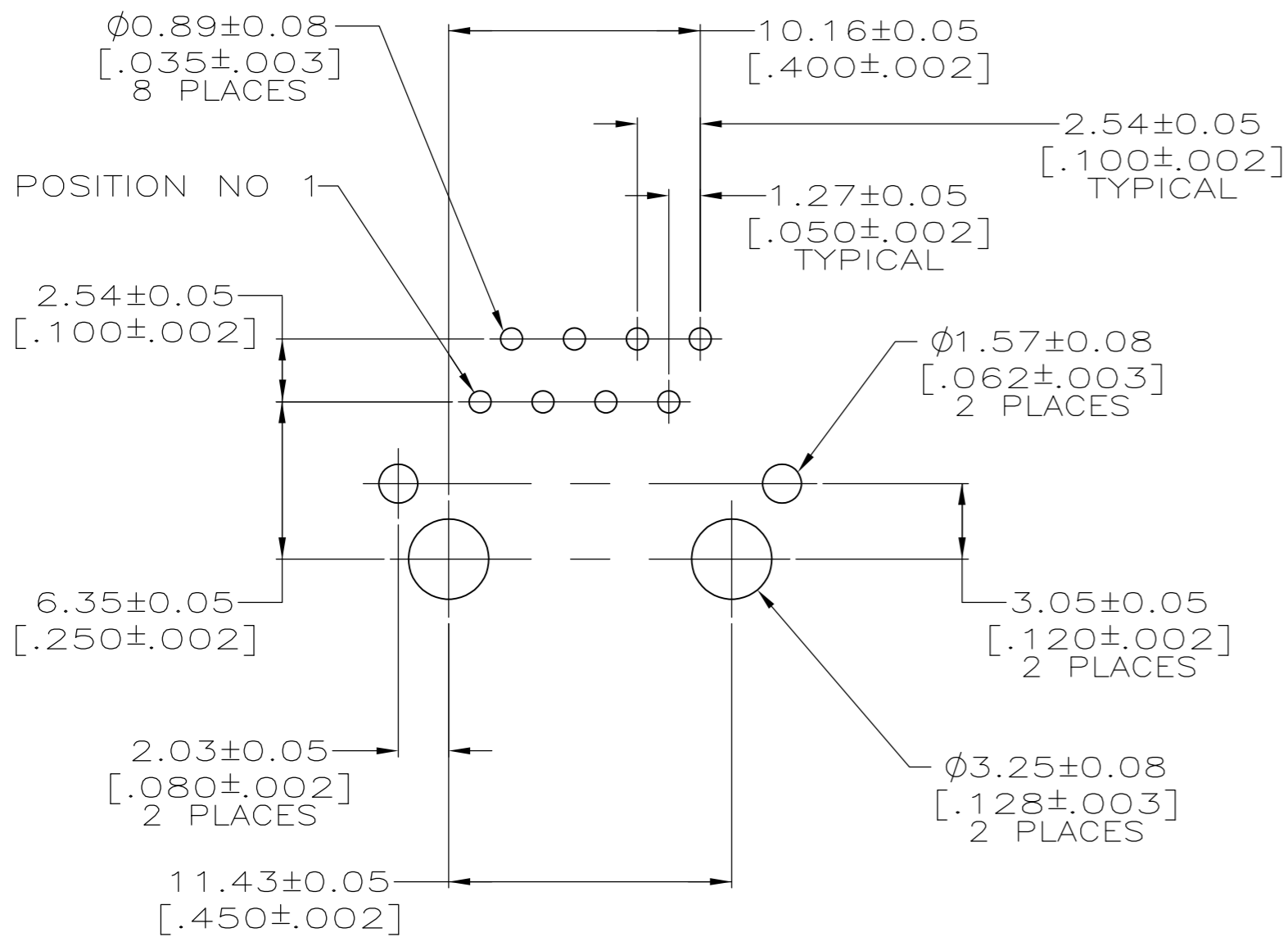


1 MATERIAL: HOUSING - NYLON, BLACK, IR REFLOW COMPATIBLE, UL 94V-0.
 TERMINALS - 0.33 [.013] THICK PHOS BRONZE PLATED WITH 1.27 μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 2.03 μm [.000080] MINIMUM BRIGHT TIN OVER 1.27 μm [.000050] MINIMUM NICKEL

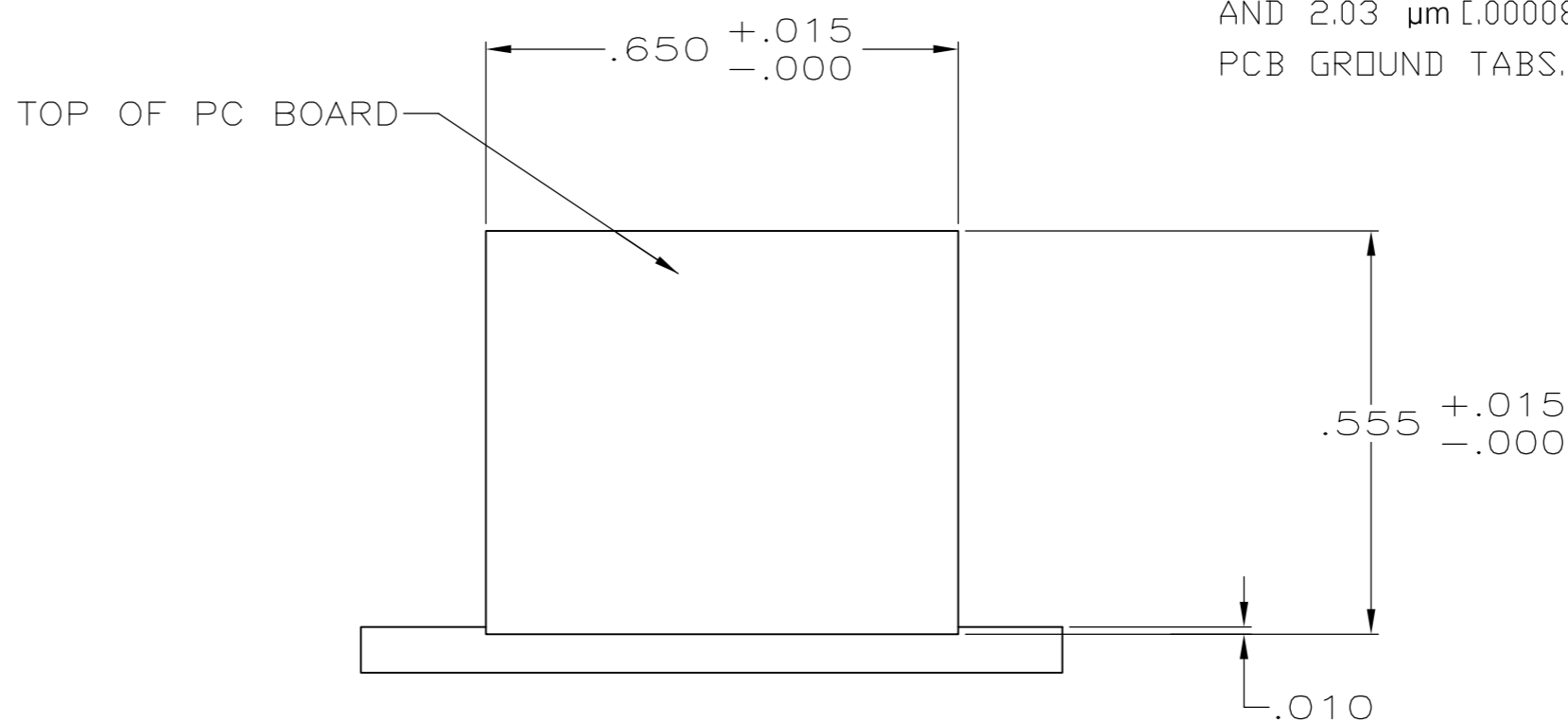
2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.

3 USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.

4 MATERIAL: HOUSING - NYLON, BLACK, IR REFLOW COMPATIBLE, UL 94V-0.
 TERMINALS - 0.33 [.013] THICK PHOS BRONZE PLATED WITH 1.27 μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27 μm [.000050] MINIMUM NICKEL AND 2.03 μm [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.



SUGGESTED PC BOARD LAYOUT
 COMPONENT SIDE
 SCALE 4:1



SUGGESTED PANEL CUTOUT
 SCALE 4:1

SUPERSEDED BY -2	4	5406298-2
	1	5406298-1
REMARK	PART NUMBER	

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	20APR2005	TE Connectivity	
		CHK	T. SPRINKLE/L.A.MAYER	MODULAR JACK ASSEMBLY, SINGLE PORT, 8 POSITION, SHIELDED, REVERSE PANEL GROUND TABS, CATEGORY 4	
		APVD	J.WESTMAN	SIZE	A2
		PRODUCT SPEC	S.FLICKINGER	CAGE CODE	00779
		APPLICATION SPEC	108-1163	DRAWING NO	C=5406298
		FINISH	114-2048	SCALE	2:1
SEE NOTE 1&4		SEE NOTE 1&4	WEIGHT	SHEET	1 OF 1
			CUSTOMER DRAWING	REV	D

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)